

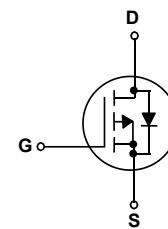
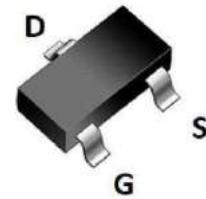


Features

- P-Channel
- Good stability and uniformity
- 100% avalanche tested
- Excellent package for good heat dissipation

V_{DS}	-20	V
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	29	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=-2.5$ V	40	mΩ
I_D	-5	A

SOT-23



Part ID	Package Type	Marking	Packing
ZT2305	SOT-23	2305	3000pcs/Reel

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	± 12	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-20	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	-20
			A
Mounted on Large Heat Sink			
I_D	Drain Current-Continuous	$T_c=25^\circ\text{C}$	-5
		$T_c=100^\circ\text{C}$	-3.1
P_D	Maximum Power Dissipation - Derate above 25°C	$T_c=25^\circ\text{C}$	1.5
		$T_c=25^\circ\text{C}$	0.53
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	83	°C/W



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 12\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
V _{G(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4	-0.7	-0.9	V
R _{D(on)}	Drain-Source On-State Resistance	$V_{GS}=-4.5\text{V}, I_D=-4.1\text{A}$	--	29	42	$\text{m}\Omega$
R _{D(on)}	Drain-Source On-State Resistance	$V_{GS}=-2.5\text{V}, I_D=-3\text{A}$	--	40	58	$\text{m}\Omega$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated) (Note 3,4)

C _{iss}	Input Capacitance	$V_{DS}=-10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	820	--	pF
C _{oss}	OutputCapacitance		--	102	--	pF
C _{rss}	ReverseTransferCapacitance		--	80	--	pF
Q _g	Total Gate Charge	$V_{DS}=-10\text{V}, I_D=-4.1\text{A}, V_{GS}=-4.5\text{V}$	--	7	--	nC
Q _{gs}	Gate-SourceCharge		--	1	--	nC
Q _{gd}	Gate-DrainCharge		--	1.4	--	nC

Switching Characteristics (Note 3,4)

T _{d(on)}	Turn-on Delay Time	$V_{DD}=-10\text{V}, I_D=-4.1\text{A}, R_L=1\Omega, R_G=1\Omega, V_{GS}=-4.5\text{V}$	--	14	--	ns
T _r	Turn-on Rise Time		--	60	--	ns
T _{d(off)}	Turn-Off Delay Time		--	20	--	ns
T _f	Turn-Off Fall Time		--	10	--	ns

Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

I _{SD}	Source-Drain Current (Body Diode) (Note 2)		--	--	-5	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-16	A
V _{SD}	Forward on voltage	$I_S=-4.1\text{A}, V_{GS}=0\text{V}$	--	--	-1.2	V
T _{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_S=4.1\text{A}$ $di/dt=100\text{A}/\mu\text{s}$	--	16	--	ns
Q _{rr}	Reverse Recovery Charge		--	7	--	nC

Notes:

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $I_{SD} \leq -4\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
- Pulse Test : Pulse width $\leq 300\text{us}$, Duty cycle $\leq 2\%$
- Essentially independent of operating temperature

Typical Performance Characteristics

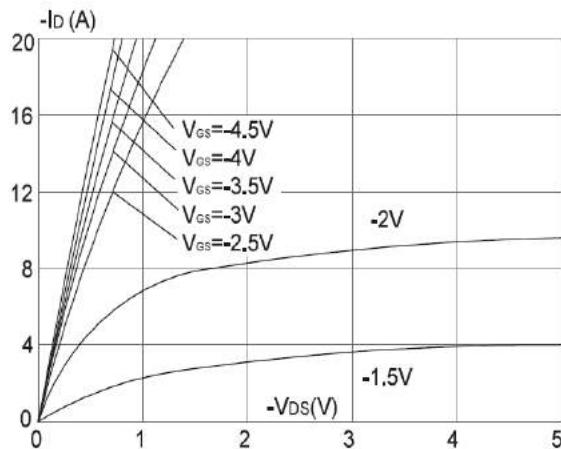


Figure 1: Output Characteristics

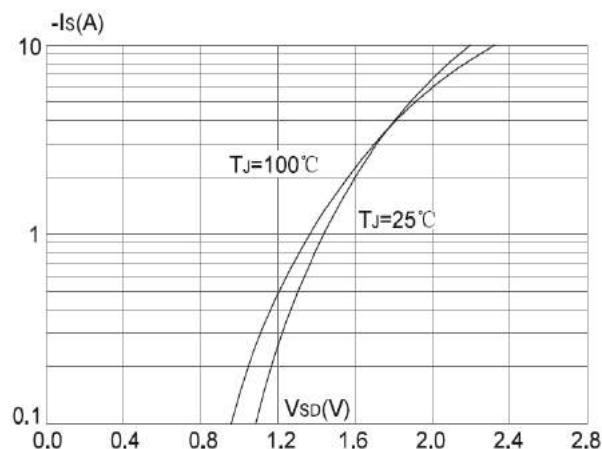


Figure 4: Body Diode Characteristics

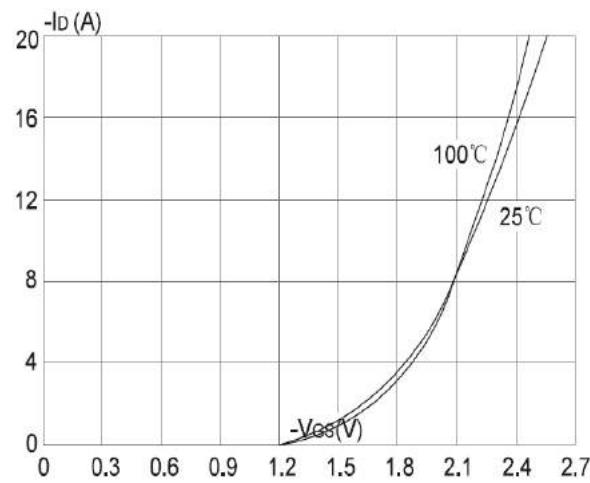


Figure 2: Typical Transfer Characteristics

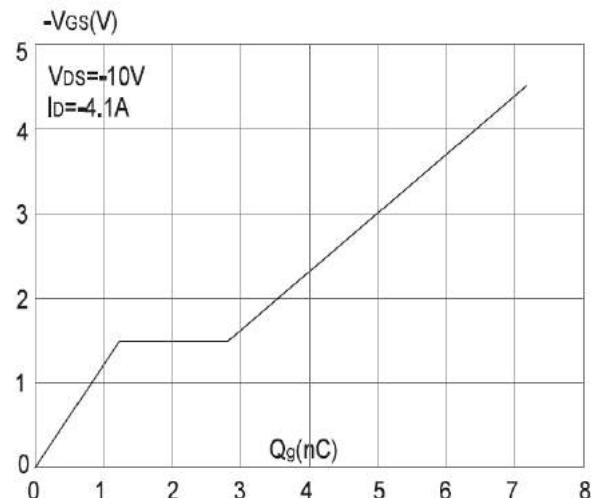


Figure 5: Gate Charge Characteristics

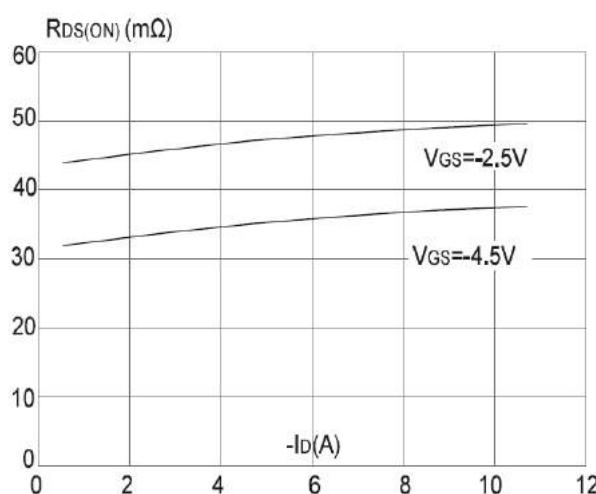


Figure 3: On-resistance vs. Drain Current

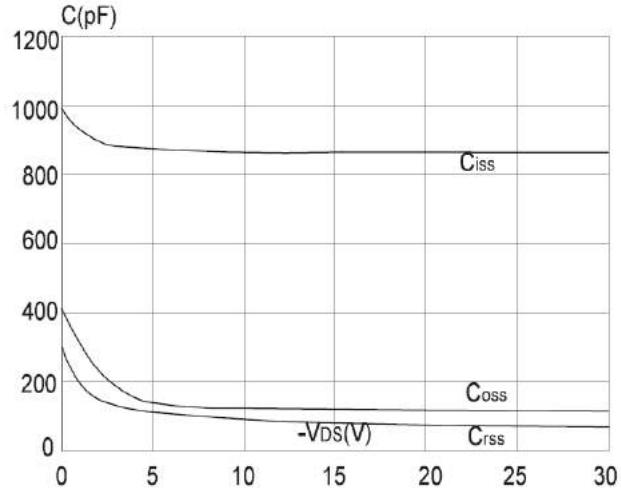


Figure 6: Capacitance Characteristics

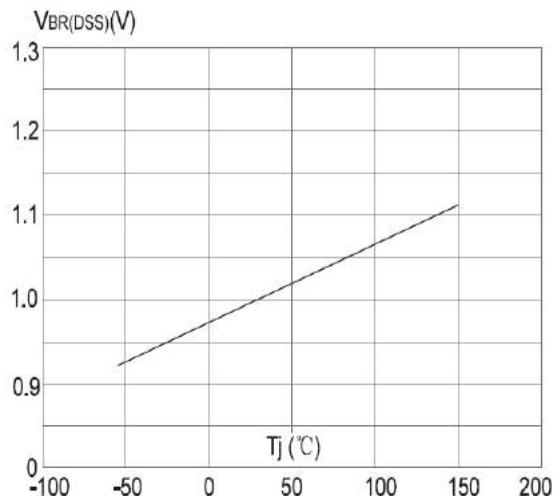


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

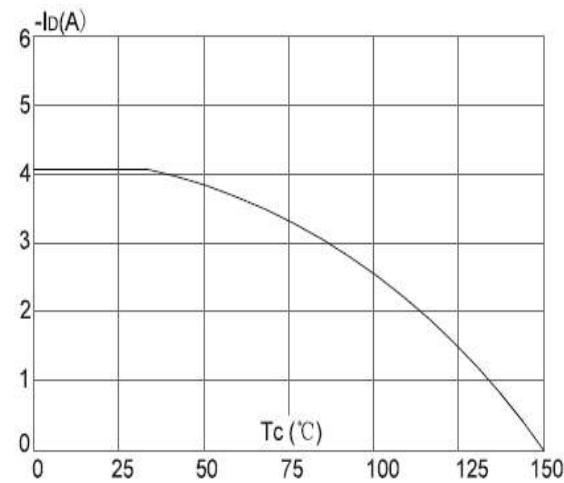


Figure 9: Maximum Drain Current vs. Case Temperature

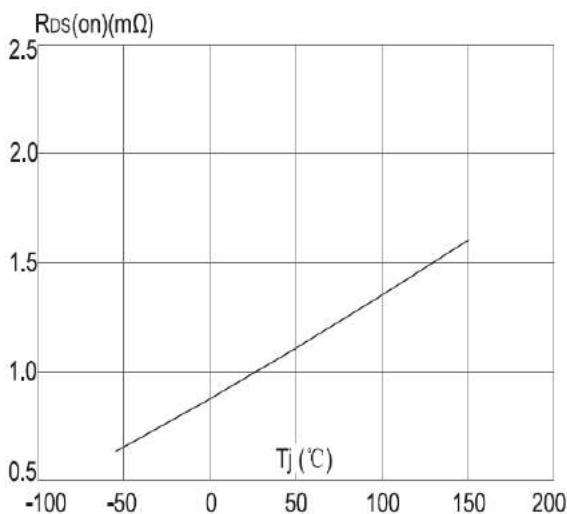


Figure 8: Normalized on Resistance vs. Junction Temperature

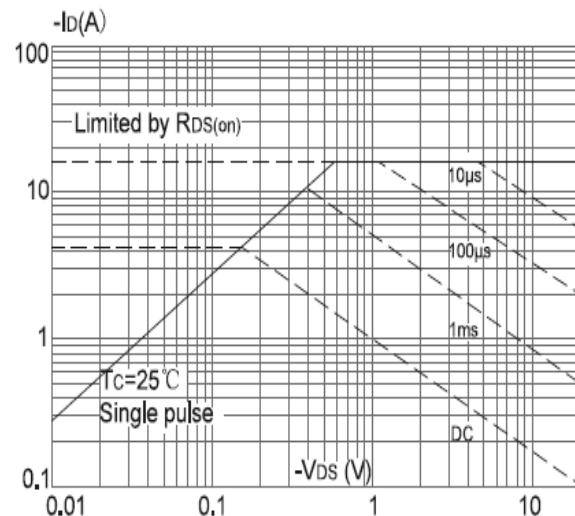


Fig.10 Safe Operating Area

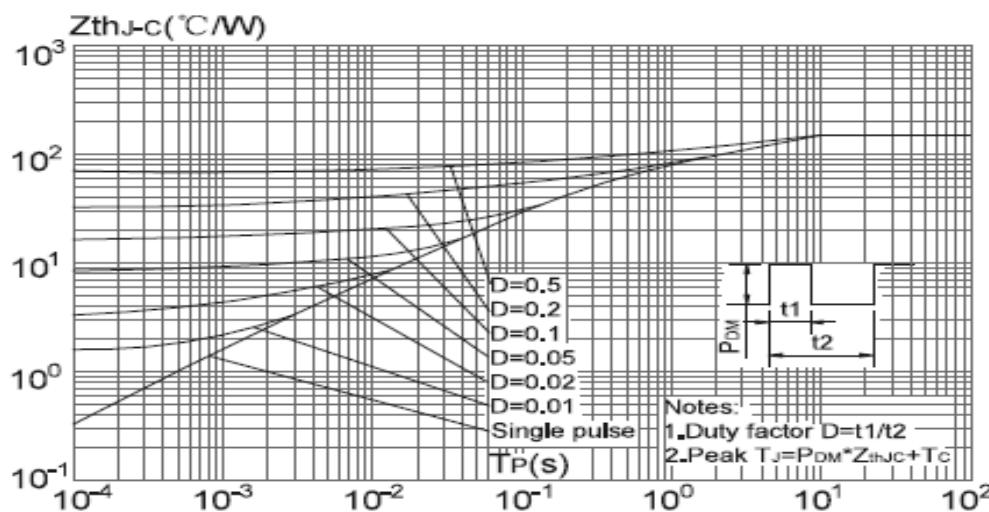
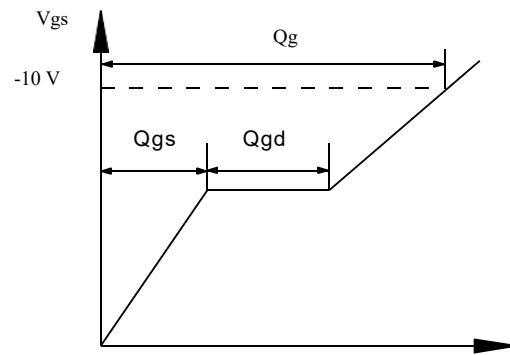
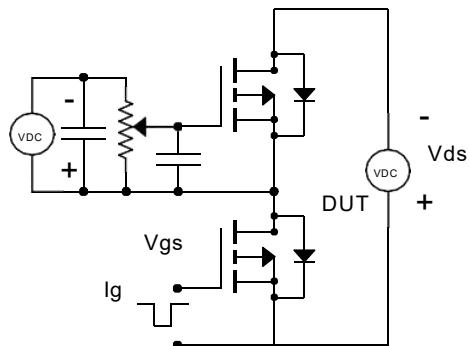


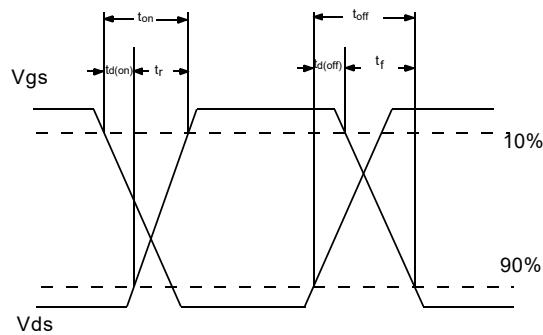
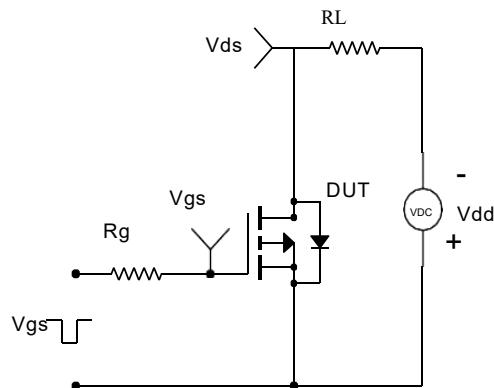
Fig. 11 Transient Thermal Response Curve



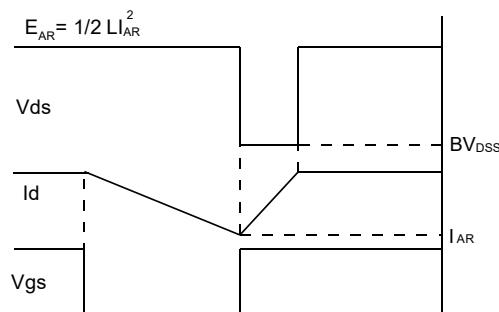
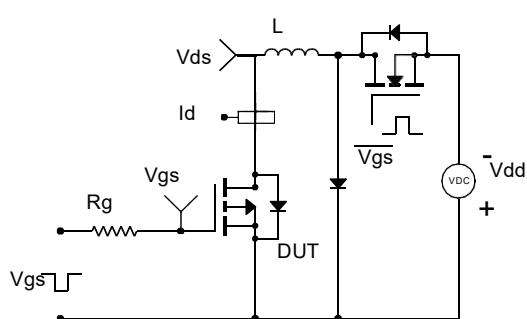
Gate Charge Test Circuit & Waveform



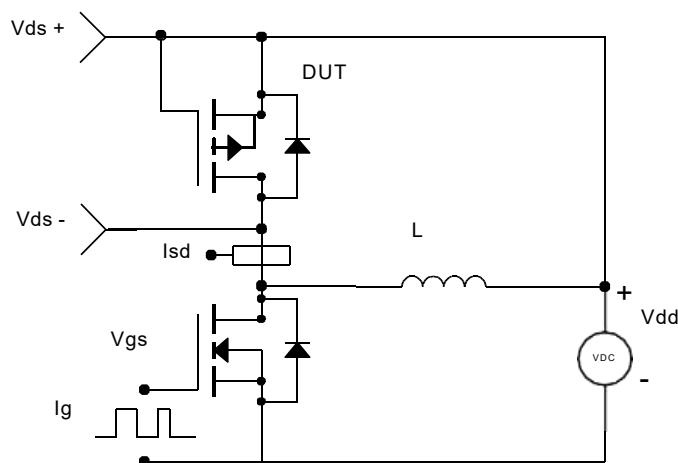
Resistive Switching Test Circuit & Waveforms



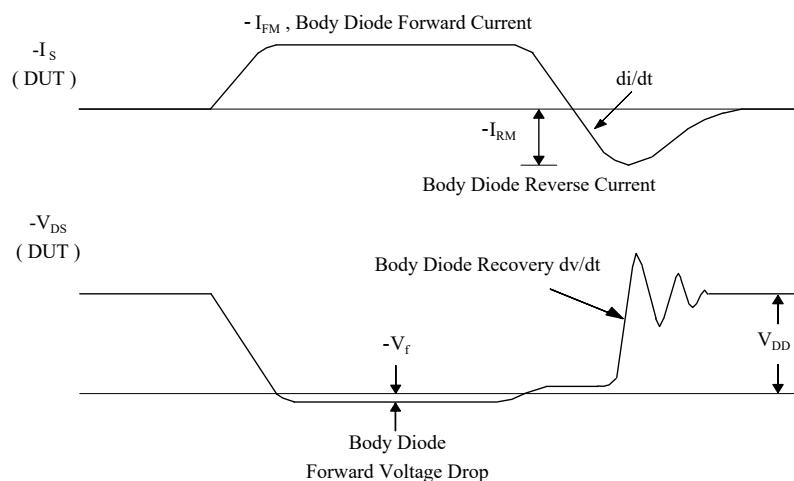
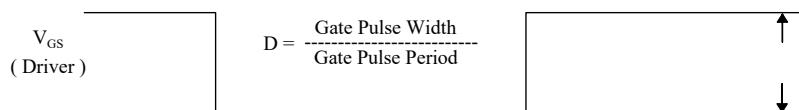
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

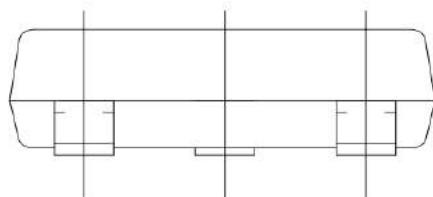
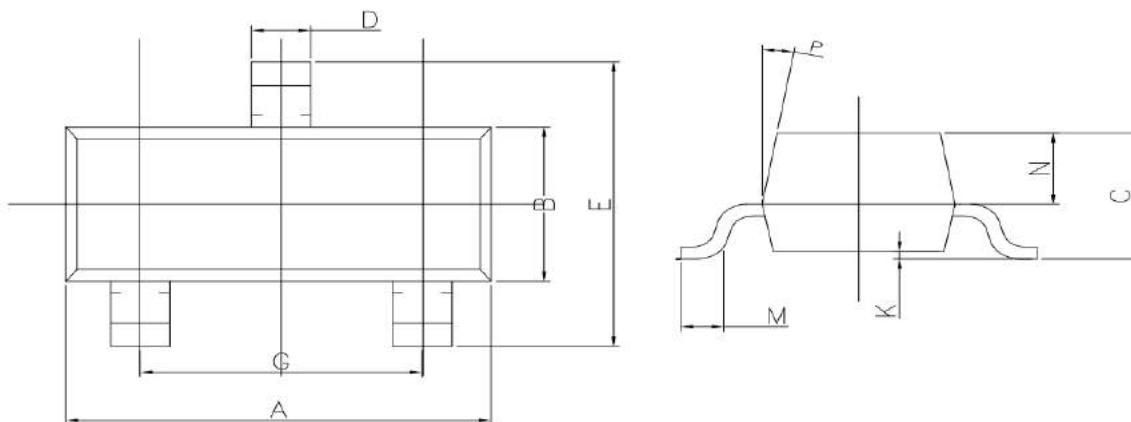


- dv/dt controlled by R_G
- I_{SD} controlled by pulse period





SOT-23 Package Information



DIM	MILLIMETERS
A	2.90 ± 0.1
B	1.30 ± 0.10
C	0.90 ~ 1.15
D	0.40 ± 0.1
E	2.40 ± 0.15
G	1.90 ± 0.10
K	0.00~0.10
M	0.30MIN
N	0.60 ± 0.10
P	10°TYP

Customer Service

Sales and Service:

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